

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of) Attorney Docket No.: **MIYOSH0008**
Seiichi AKAGI et al.)
Serial No.: 10/598,515) Confirmation No.: 6701
Filed: September 1, 2006) Group Art Unit: 1796
For: **SEALANT EPOXY-RESIN MOLDING**) Examiner: Hannah J. PAK
MATERIAL, AND ELECTRONIC)
COMPONENT DEVICE) Date: May 20, 2010
)

AMENDMENT (F)

MAIL STOP: AMENDMENT
U.S. Patent and Trademark Office
Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In view of the Telephone Interview Summary (E) filed on April 7, 2010, and in view of the telephone discussion conducted between Examiner Hannah Pak (571-270-5456) and Applicants' attorney, Wesley Ashton, on May 20, 2010, please amend the application identified above as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected by the Listing of Claims that begins on page 3 of this paper.

Remarks/Arguments begin on page 12 of this paper.